

## POLISHING APPARATUS AND METHOD FOR FORMING AN INTEGRATED CIRCUIT

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### Abstract of the Disclosure

10 In one embodiment, a semiconductor substrate (38) is  
uniformly polished using a polishing pad (16) that has a first  
polishing region (26), a second polishing region (28), and a third  
polishing region (30). The semiconductor substrate (38) is aligned to  
the polishing pad (16), such that the center of the semiconductor  
substrate (38) overlies the second polishing region (28), and the edge  
of the semiconductor substrate overlies the first polishing region (26)  
and the third polishing region (30). During polishing, the  
15 semiconductor substrate (38) is not radially oscillated over the  
surface of the polishing pad, and as a result a more uniform  
polishing rate is achieved across the semiconductor substrate (38).  
This allows the semiconductor substrate (38) to be uniformly polished  
from center to edge, and increases die yield because die located on  
20 the semiconductor substrate (38) are not over polished.